# PNP SILICON PLANAR EPITAXIAL TRANSISTORS

**PN2907**
**PN2907A**

TO-92

**TO-92**
**Plastic Package**
**RoHS compliant**

## FEATURE:

1. This product is available in AEC-Q101 Compliant and PPAP Capable also.

**Note:** For AEC-Q101 compliant products, please use suffix -AQ in the part number while ordering.

## APPLICATIONS:

Complementary Silicon Transistors for Switching and Linear Applications

## ABSOLUTE MAXIMUM RATINGS (Ta = 25 ℃ Unless otherwise specified)

| PARAMETER | SYMBOL | PN2907 | PN2907A | UNIT |
|---|---|---|---|---|
| Collector Emitter Voltage | $V_{CEO}$ | 40 | 60 | V |
| Collector Base Voltage | $V_{CBO}$ | 60 | 60 | V |
| Emitter Base Voltage | $V_{EBO}$ | 5 | 5 | V |
| Collector Current Continuous | $I_C$ | 600 | | mA |
| Power Dissipation@ Ta=25ºC | $P_D$ | 625 | | mW |
| Derate Above 25ºC | | 5.0 | | mW/°C |
| Power Dissipation@ Tc=25ºC | $P_D$ | 1.5 | | W |
| Derate Above 25ºC | | 12 | | mW/°C |
| Operating And Storage Junction Temperature Range | $T_1$, $T_{stg}$ | -55 to +150 | | °C |

## THERMAL RESISTANCE

| | | | |
|---|---|---|---|
| Junction to ambient | $R_{th(j-a)}$ | 200 | °C/W |
| Junction to case | $R_{th(j-c)}$ | 83.3 | °C/W |

## ELECTRICAL CHARACTERISTICS at (Ta = 25 ℃ Unless otherwise specified)

| PARAMETER | SYMBOL | TEST CONDITION | | PN2907 | PN2907A | UNIT |
|---|---|---|---|---|---|---|
| Collector Emitter Voltage | $BV_{CEO}$ | $I_C$=10mA,$I_B$=0 | Max | 40 | 60 | V |
| Collector Base Voltage | $BV_{CBO}$ | $I_C$=10μA,$I_E$=0 | Max | 60 | 60 | V |
| Emitter Base Voltage | $B_{VEBO}$ | $I_E$=10μA, $I_C$=0 | Max | 5 | 5 | V |
| Collector Cut off Current | $I_{CBO}$ | $V_{CB}$=50V, $I_E$ = 0 | Max | 20 | 10 | nA |
| | | $V_{CB}$=50V, $I_E$ = 0 $T_a$= 150ºC | Max | 20 | 10 | μA |
| | $I_{CEX}$ | $V_{CE}$ =30V, $V_{EB}$=0.5V | Max | 50 | 50 | nA |
| | $I_{CEO}$ | $V_{CE}$=10V, $I_B$ = 0 | Max | 10 | 10 | nA |
| Emitter Cut off Current | $I_{EBO}$ | $V_{EB}$=3V, $I_C$ = 0 | Max | 10 | 10 | nA |
| Base Cut off Current | $I_{BEX}$ | $V_{CE}$ =30V, $V_{EB}$=0.5V | Max | 50 | 50 | nA |
| DC Current Gain | $h_{FE}$ | $V_{CE}$=10V,$I_C$=0.1mA | Min | 35 | 75 | |
| | | $V_{CE}$=10V,$I_C$=1mA | Min | 50 | 100 | |
| | | $V_{CE}$=10V,$I_C$=10mA | Min | 75 | 100 | |
| | | $V_{CE}$=10V [1],$I_C$=150mA | | 100 ~ 300 | 100 ~ 300 | |
| | | $V_{CE}$=10V [1],$I_C$=500mA | Min | 30 | 50 | |
| Collector Emitter Saturation Voltage | $V_{CE(sat)}$ | $I_C$=150mA,$I_B$=15mA | Max | 0.4 | 0.4 | V |
| | | $I_C$=500mA,$I_B$= 50mA | Max | 1.6 | 1.6 | V |
| Base Emitter Saturation Voltage | $V_{BE(sat)}$ | $I_C$=150mA,$I_B$=15mA | Max | 1.3 | 1.3 | V |
| | | $I_C$=500mA,$I_B$= 50mA | Max | 2.6 | 2.6 | V |
| **DYNAMIC CHARACTERISTICS** | | | | | | |
| Transition Frequency | $f_T$ | $I_C$=50mA, $V_{CE}$=20V, f=100MHz | Min | 200 | 200 | MHz |
| Output Capacitance | $C_{ob}$ | $I_E$=0,$V_{CB}$=10V,f=1MHz | Max | 8 | 8 | pF |
| Input Capacitance | $C_{ib}$ | Ic=0,$V_{EB}$=2V,f=1MHz | Max | 30 | 30 | pF |
| **SWITCHING CHARCTERISTICS** | | | | | | |
| Delay Time | $t_d$ | $I_C$ =150mA, $I_{B1}$= 15mA $V_{CC}$ =30V | Max | 10 | 10 | ns |
| Rise Time | $t_r$ | | Max | 40 | 40 | |
| Turn on Time | $t_{on}$ | | Max | 50 | 50 | |
| Storage Time | $t_s$ | $I_C$ =150mA, $I_{B1}$=15mA $I_{B2}$=15mA, $V_{CC}$ =6V | Max | 80 | 80 | |
| Fall Time | $t_f$ | | Max | 30 | 30 | |
| Turn off Time | $t_f$ | | Max | 110 | 110 | |

**Note:**

1. Pulse Condition: = Width ≤300us, Duty Cycle ≤1%
2. For PNP device voltage and current values will be negative (-).

## Recommended Reflow Solder Profiles

The recommended reflow solder profiles for Pb and Pb-free devices are shown below.

Figure 1 shows the recommended solder profile for devices that have Pb-free terminal plating, and where a Pb-free solder is used.

Figure 2 shows the recommended solder profile for devices with Pb-free terminal plating used with leaded solder, or for devices with leaded terminal plating used with a leaded solder.

**Figure 1**

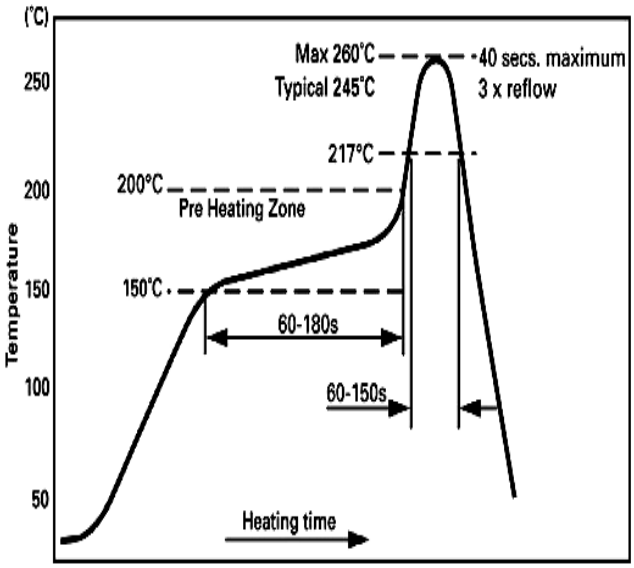
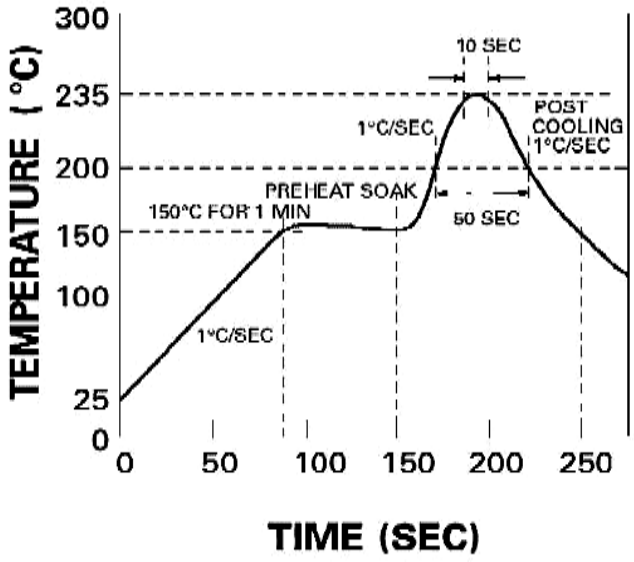



**Figure 2**

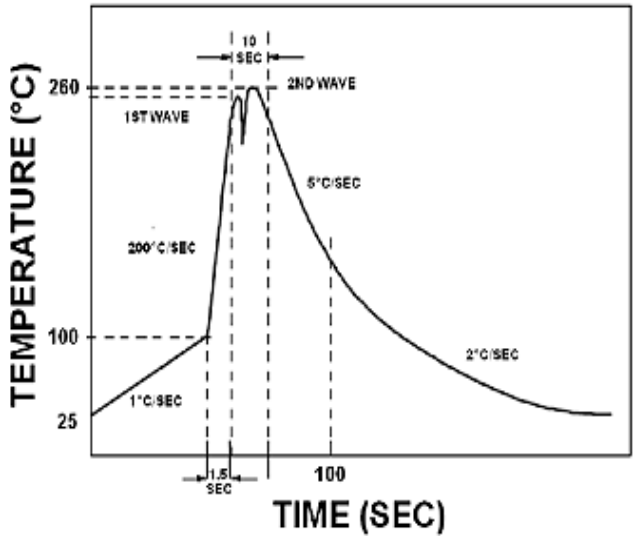



**Reflow profiles in tabular form**

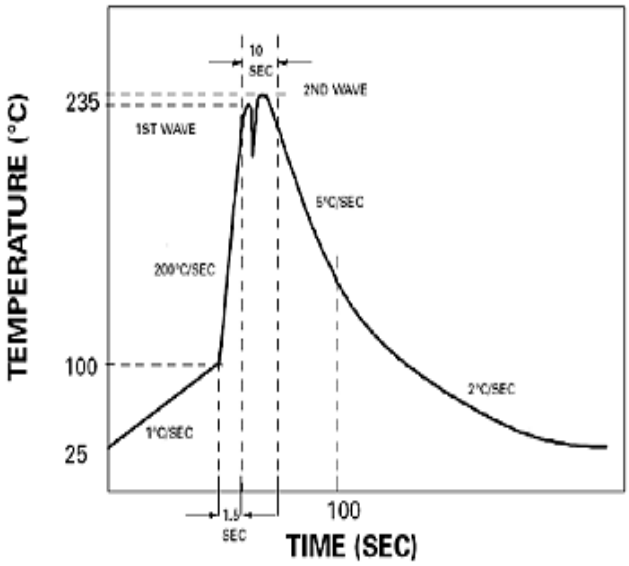
| Profile Feature | Sn-Pb System | Pb-Free System |
|---|---|---|
| Average Ramp-Up Rate | ~3°C/second | ~3°C/second |
| **Preheat**<br>– Temperature Range<br>– Time | <br>150-170°C<br>60-180 seconds | <br>150-200°C<br>60-180 seconds |
| Time maintained above:<br>– Temperature<br>– Time | <br>200°C<br>30-50 seconds | <br>217°C<br>60-150 seconds |
| Peak Temperature | 235°C | 260°C max. |
| Time within +0 -5°C of actual Peak | 10 seconds | 40 seconds |
| Ramp-Down Rate | 3°C/second max. | 6°C/second max. |

## Recommended Wave Solder Profiles

The Recommended solder Profile For Devices with Pb-free terminal plating where a Pb-free solder is used




The Recommended solder Profile For Devices with Pb-free terminal plating used with leaded solder, or for devices with leaded terminal plating used with leaded solder




### Wave Profiles in Tabular Form

| Profile Feature | Sn-Pb System | Pb-Free System |
|---|---|---|
| Average Ramp-Up Rate | ~200°C/second | ~200°C/second |
| Heating rate during preheat | Typical 1-2, Max 4°C/sec | Typical 1-2, Max 4°C/Sec |
| Final preheat Temperature | Within 125°C of Solder Temp | Within 125°C of Solder Temp |
| Peak Temperature | 235°C | 260°C max. |
| Time within +0 -5°C of actual Peak | 10 seconds | 10 seconds |
| Ramp-Down Rate | 5°C/second max. | 5°C/second max |

## Test Circuits

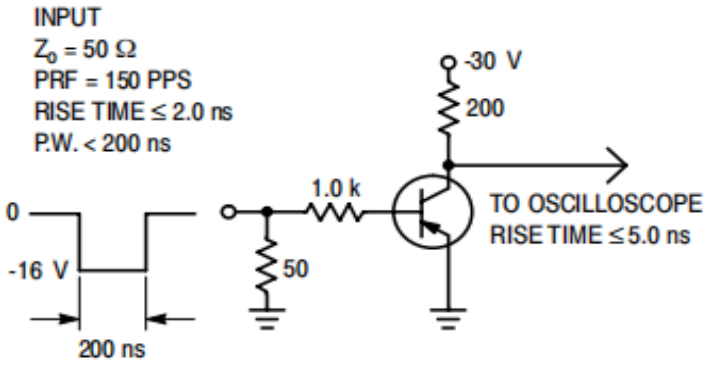



Figure 1. Delay and Rise Time Test Circuit

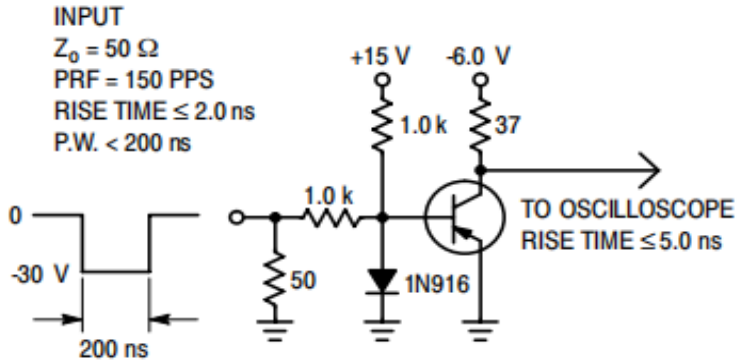



Figure 2. Storage and Fall Time Test Circuit

## TYPICAL CHARACTERISTIC CURVES

Figure 3. DC Current Gain

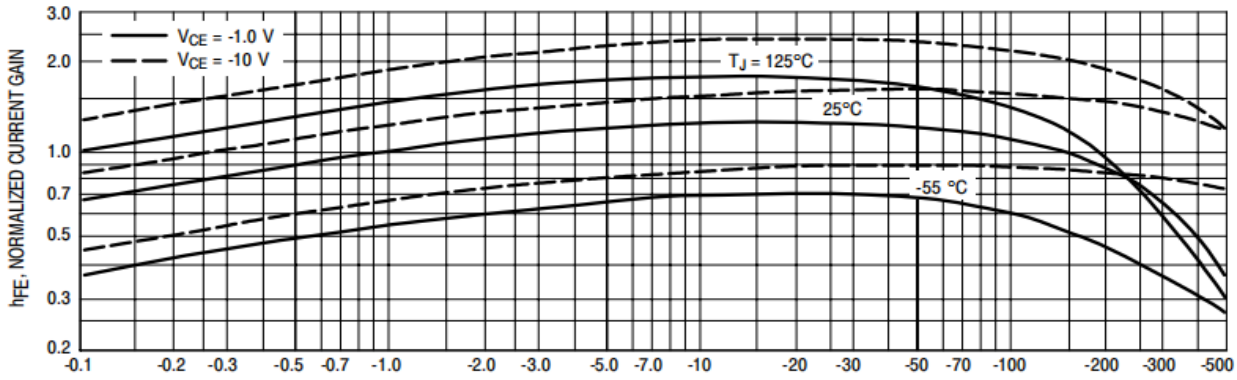



Figure 4. Collector Saturation Region

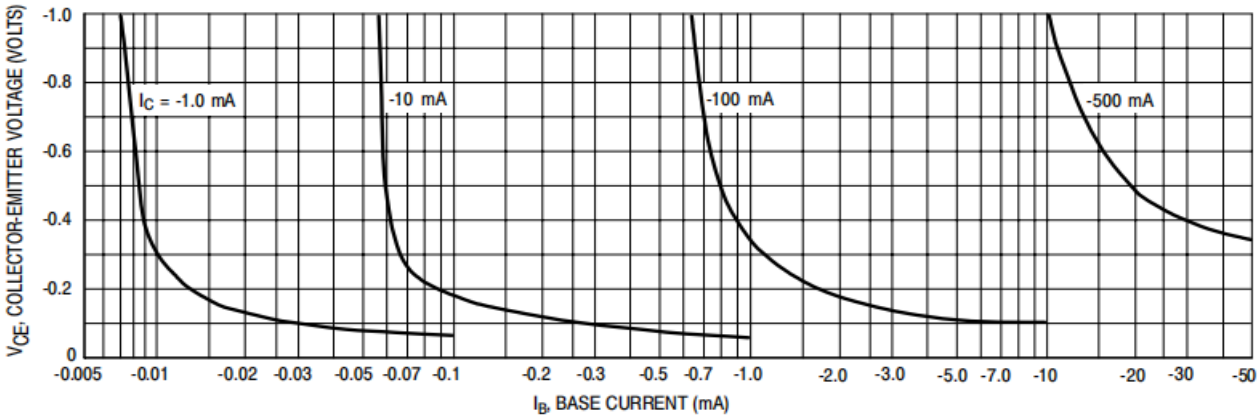



Figure 5. Turn-On Time

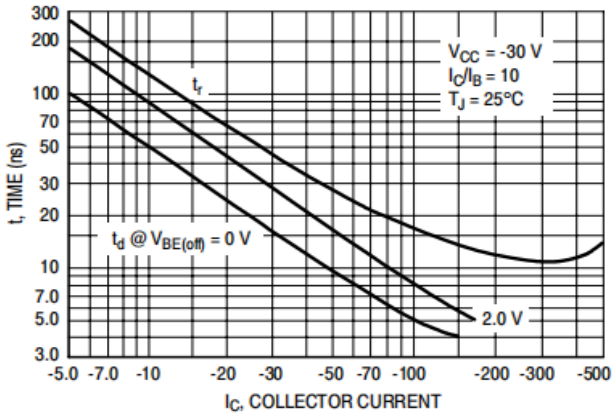
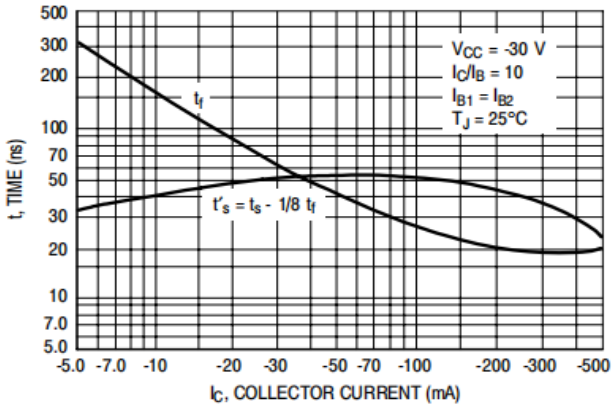



Figure 6. Turn-On Time



## TYPICAL CHARACTERISTIC CURVES

Figure 7. Frequency Effects

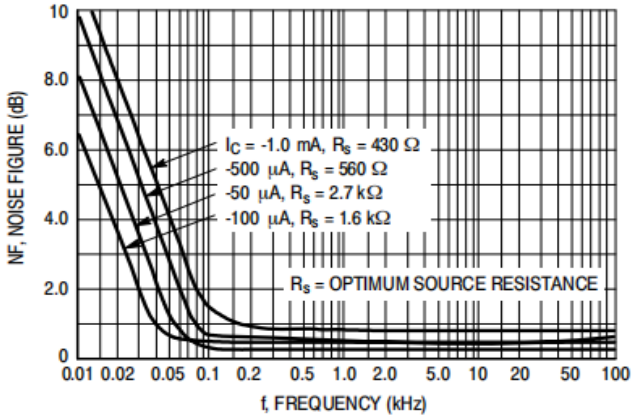



Figure 8. Source Resistance Effects

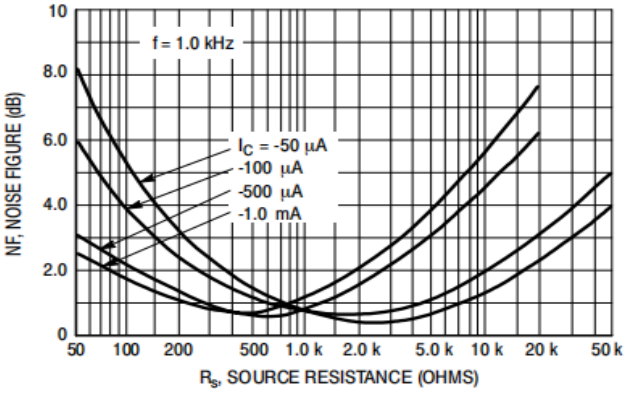



Figure 9. Capacitance

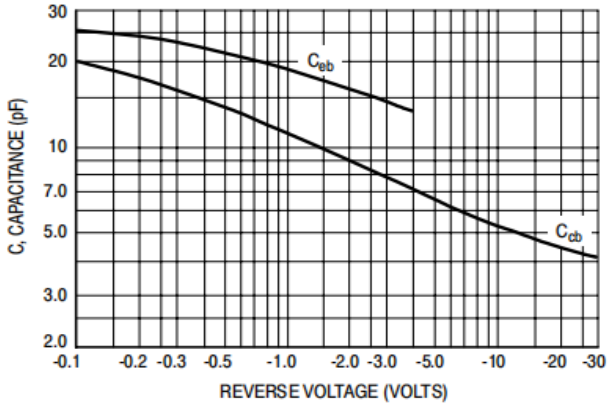



Figure 10. Current-Gain — Bandwidth Product

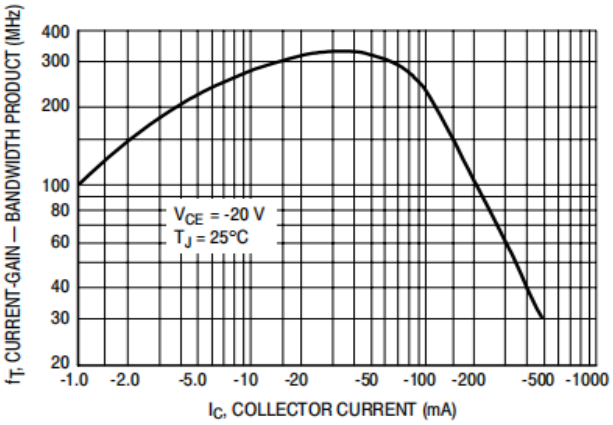



Figure 11. “On” Voltage

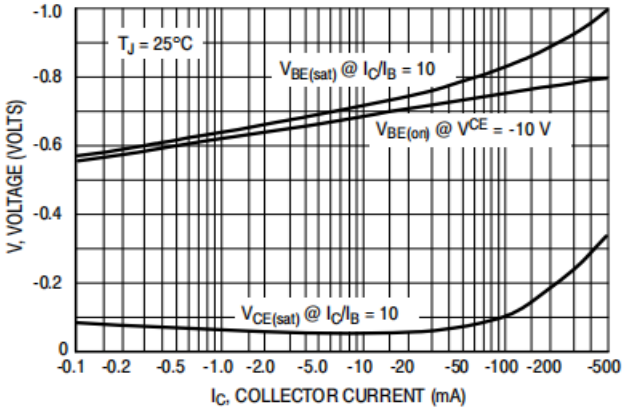
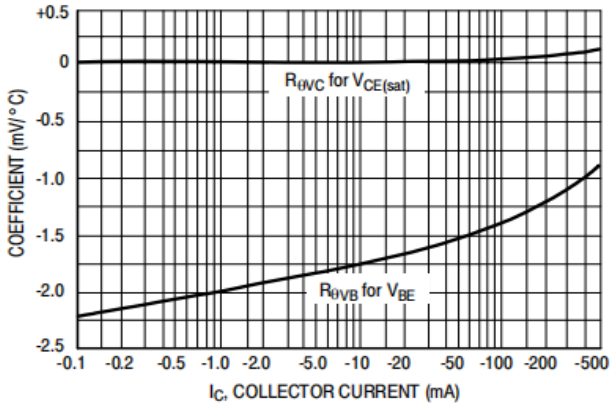
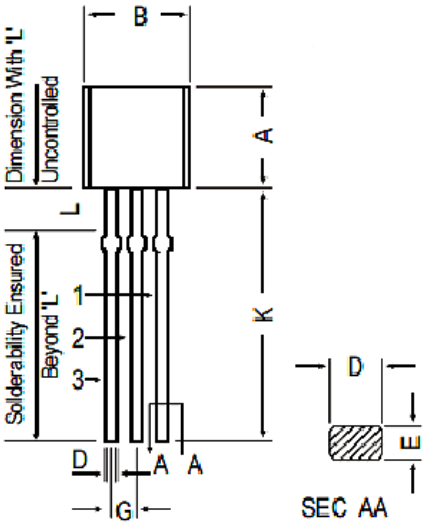



Figure 12. Temperature Coefficients



## PACKAGE DETAILS

TO-92 Leaded Plastic Package

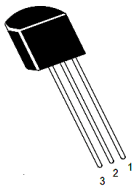



| DIM | MIN | MAX |
|---|---|---|
| A | 4.32 | 5.33 |
| B | 4.45 | 5.20 |
| C | 3.18 | 4.19 |
| D | 0.41 | 0.55 |
| E | 0.35 | 0.50 |
| F | 5° | |
| G | 1.14 | 1.40 |
| H | 1.20 | 1.53 |
| K | 12.70 | |
| L | 1.982 | 2.082 |

All dimensions are in mm

### PIN CONFIGURATION

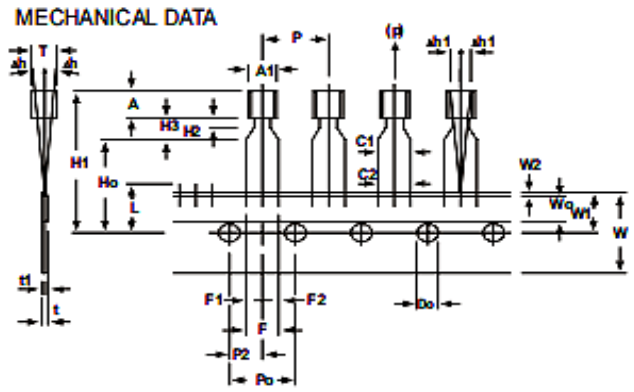
1. Emitter
2. Base
3. Collector

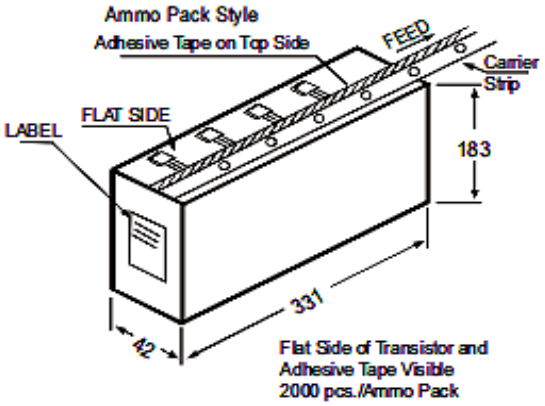



## Packaging Information

| PACKAGE | STANDARD PACK | | INNER CARTON BOX | | OUTER CARTON BOX | | |
|---|---|---|---|---|---|---|---|
| | Details | Net Weight/Qty | Size | Qty | Size | Qty | Gr Wt |
| TO-92 Bulk | 1K/polybag | 200 gm/1K pcs | 3" x 7.5" x 7.5" | 5K | 17" x 15" x 13.5" | 80K | 23 kgs |
| TO-92 T&A | 2K/ammo box | 645 gm/2K pcs | 12.5" x 8" x 1.8" | 2K | 17" x 15" x 13.5" | 32K | 12.5 kgs |

## TO-92 Transistors on Tape and Ammo Pack




| ITEM | SYMBOL | SPECIFICATION | | | | REMARKS |
|---|---|---|---|---|---|---|
| | | MIN. | NOM. | MAX. | TOL. | |
| BODY WIDTH | A1 | 4.0 | | 4.8 | | |
| BODY HEIGHT | A | 4.8 | | 5.2 | | |
| BODY THICKNESS | T | 3.9 | | 4.2 | | |
| PITCH OF COMPONENT | P | | 12.7 | | %%P1 | |
| FEED HOLE PITCH | Po | | 12.7 | | %%P0.3 | CUMULATIVE PITCH ERROR 1.0 mm/20 PITCH |
| FEED HOLE CENTRE TO COMPONENT CENTRE | P2 | | 6.35 | | %%P0.4 | TO BE MEASURED AT BOTTOM OF CLINCH |
| DISTANCE BETWEEN OUTER LEADS | F | | 5.08 | | +0.6 -0.2 | |
| COMPONENT ALIGNMENT SIDE VIEW | Δh | | 0 | 1.0 | | AT TOP OF BODY |
| COMPONENT ALIGNMENT FRONT VIEW | Δh1 | | 0 | 1.3 | | AT TOP OF BODY |
| TAPE WIDTH | W | | 18 | | %%P0.5 | |
| HOLD-DOWN TAPE WIDTH | Wo | | 6 | | %%P0.2 | |
| HOLE POSITION | W1 | | 9 | | +0.7 -0.5 | |
| HOLD-DOWN TAPE POSITION | W2 | | 0.5 | | %%P0.2 | |
| LEAD WIRE CLINCH HEIGHT | Ho | | 16 | | %%P0.5 | |
| COMPONENT HEIGHT | H1 | | | 23.25 | | |
| LENGTH OF SNIPPED LEADS | L | | | 11.0 | | |
| FEED HOLE DIAMETER | Do | | 4 | | %%P0.2 | |
| TOTAL TAPE THICKNESS | t | | | 1.2 | | t1 0.3 - 0.6 |
| LEAD - TO - LEAD DISTANCE | F1,F2 | | 2.54 | | +0.4, -0.1 | |
| STAND OFF | H2 | 0.45 | | 1.45 | | |
| CLINCH HEIGHT | H3 | | | 3.0 | | |
| LEAD PARALLELISM | \| C1 - C2 \| | | | 0.22 | | |
| PULL - OUT FORCE | (P) | 6N | | | | |

NOTES

1. Maximum Alignment Deviation Between Leads Not to be Greater Than 0.2 mm
2. Maximum Non-Cumulative Variation Between Tape Feed Hole shall not exceed 1 mm In 20 Pitches.
3. Hold down tape not to exceed beyond the edge(S) of carrier tape and there shall be exposure of adhesive.
4. No more then 3 Consecutive Missing Components is permitted.
5. A tape Trailer, Having at least three feed hole is required after the last component.
6. Splices shall not interfere with the sprocket feed holes.

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# Recommended Product Storage Environment for Discrete Semiconductor Devices

This storage environment assumes that the Diodes and transistors are packed properly inside the original packing supplied by CDIL.

- Temperature 5 °C to 30 °C
- Humidity between 40 to 70 %RH
- Air should be clean.
- Avoid harmful gas or dust.
- Avoid outdoor exposure or storage in areas subject to rain or water spraying .
- Avoid storage in areas subject to corrosive gas or dust. Product shall not be stored in areas exposed to direct sunlight.
- Avoid rapid change of temperature.
- Avoid condensation.
- Mechanical stress such as vibration and impact shall be avoided.
- The product shall not be placed directly on the floor.
- The product shall be stored on a plane area. They should not be turned upside down. They should not be placed against the wall.

## Shelf Life of CDIL Products

The shelf life of products is the period from product manufacture to shipment to customers. The product can be unconditionally shipped within this period. The period is defined as 2 years.
If products are stored longer than the shelf life of 2 years the products shall be subjected to quality check as per CDIL quality procedure.
The products are further warranted for another one year after the date of shipment subject to the above conditions in CDIL original packing.

## Floor Life of CDIL Products and MSL Level

When the products are opened from the original packing, the floor life will start.
For this, the following JEDEC table may be referred:

| JEDEC MSL Level | | |
|---|---|---|
| **Level** | **Time** | **Condition** |
| 1 | Unlimited | ≤30 °C / 85% RH |
| 2 | 1 Year | ≤30 °C / 60% RH |
| 2a | 4 Weeks | ≤30 °C / 60% RH |
| 3 | 168 Hours | ≤30 °C / 60% RH |
| 4 | 72 Hours | ≤30 °C / 60% RH |
| 5 | 48 Hours | ≤30 °C / 60% RH |
| 5a | 24 Hours | ≤30 °C / 60% RH |
| 6 | Time on Label(TOL) | ≤30 °C / 60% RH |

## Customer Notes

**Component Disposal Instructions**

1. CDIL Semiconductor Devices are RoHS compliant, customers are requested to please dispose as per prevailing Environmental Legislation of their Country.
2. In Europe, please dispose as per EU Directive 2002/96/EC on Waste Electrical and Electronic Equipment (WEEE).

## Disclaimer

The product information and the selection guides facilitate selection of the CDIL's Semiconductor Device(s) best suited for application in your product(s) as per your requirement. It is recommended that you completely review our Data Sheet(s) so as to confirm that the Device(s) meet functionality parameters for your application. The information furnished in the Data Sheet and on the CDIL Web Site/CD are believed to be accurate and reliable. CDIL however, does not assume responsibility for inaccuracies or incomplete information. Furthermore, CDIL does not assume liability whatsoever, arising out of the application or use of any CDIL product; neither does it convey any license under its patent rights nor rights of others. These products are not designed for use in life saving/support appliances or systems. CDIL customers selling these products (either as individual Semiconductor Devices or incorporated in their end products), in any life saving/support appliances or systems or applications do so at their own risk and CDIL will not be responsible for any damages resulting from such sale(s).

CDIL strives for continuous improvement and reserves the right to change the specifications of its products without prior notice.

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Rev01 02082022EM